


Standardized Information for Process/Product Change Notification (PCN)

Customer				
Customer		Name Customer:	Digi-key Corporation	
		Contact Email address:	DigiKey.SupplierInfo@digkey.com	
1.1 Company		Site submitting the change:	Melexis Belgium	
		Affected site:	<table border="1" style="width: 100%; text-align: center;"> <tr> <td>Melexis Supplier</td> <td>Melexis Corbeil</td> <td></td> </tr> </table>	Melexis Supplier
Melexis Supplier	Melexis Corbeil			
1.3 Title of PCN		Active Second Source		
1.4 Product Category		Active Components - Integrated Circuits		
1.5 Issue date		Jan 5 2018		

2. PCN Team	
2.1 Contact supplier	
2.1.1 Phone	+3257226142
2.1.2 Email	contact-PCN@melexis.com

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PW-13	PROCESS - WAFER PRODUCTION	Move of all or part of wafer fab to a different location/site/subcontractor
#2	SEM-TF-01	TEST FLOW	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor

4. Description of change		
	Old	New
Change #1	Wafer fab location: X-fab Kuching (Sarawak / Malaysia)	Wafer fab location: X-fab Corbeil (France / Europe) + X-fab Kuching (Sarawak / Malaysia)
Change #2	Electrical wafer test location: currently released locations	Electrical wafer test location: currently released locations + Melexis Corbeil

5. Reason / motivation for change	
5.1 Motivation	As a responsible and future oriented player, Melexis is protecting it`s customers. This includes to secure the supply chain against environmental and/or material based events (contingency plan). The increase in business leads to wafer demand beyond X-Fab Kuching capability.

6. Marking of parts / traceability of change	
6.1 Description	Lots produced at Xfab Corbeil will have a different lot ID-number. The first letter of the lot ID will start with "F".

7. Timing / schedule		
7.1 Date of qualification results	End Q4 2018	
7.2 Intended start of delivery	End of Q1 2019	
7.3 Qualification samples available?	Yes, on request	

8. Qualification / validation	
8.1 Description (e.g. qual. plan/report)	Available as end of Q4 2018
8.2 Qualification report and qualificati	Available as of January 2019

9. Input to customer for risk assessment process
Second source is needed to avoid capacity constraints regarding wafer material supply and test throughput

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

See presentation: XFabTransfer_Corbeil.pdf

11. Affected parts

11.1 Current			11.2 New (if applicable)	
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Package Name	11.2.2 Supplier Part Name	11.2.4 Package Name
NA	MLX81106KDC-CAA-000-RE	SOIC8 GR		
NA	MLX81107KLW-CAE-000-RE	QFN_WF20/5x5 GR		
NA	MLX81108KDC-CAE-000-RE	SOIC8 GR		